Full Modem Control with RS-232

Project Title:

Designed for:

Assembly Variant:

Public Release

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Drawn By: SUNIL DWIVEDI

Engineer:

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Not in version control

SVN Rev: TIDA-00557

Number: Rev: A0
You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

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<th>Label Text</th>
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<td>ChangeMe!</td>
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<tr>
<td>002</td>
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**Label Table**

**PCB Label**

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